



Material Content Data Sheet



Sales Product Name		BSC080N03LS G		Issued		19. January 2018		
MA#		MA000444122						
Package		PG-TDSON-8-5		Weight*		118.64 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.804	0.68	0.68	6776	6776
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		319	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	copper	7440-50-8	37.762	31.84	31.88	318299	318714
wire	non noble metal	copper	7440-50-8	0.059	0.05	0.05	497	497
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		735	
	plastics	epoxy resin	-	6.188	5.22		52162	
	inorganic material	silicondioxide	60676-86-0	37.304	31.44	36.73	314443	367340
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12236	12236
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1395	1395
solder	non noble metal	tin	7440-31-5	0.022	0.02		187	
	noble metal	silver	7440-22-4	0.028	0.02		234	
	non noble metal	lead	7439-92-1	1.060	0.89	0.93	8936	9357
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.54	9.55	95418	95543
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.79	18.82	187898	188142
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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